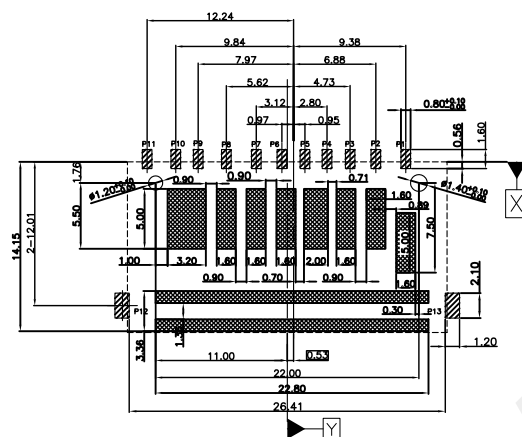
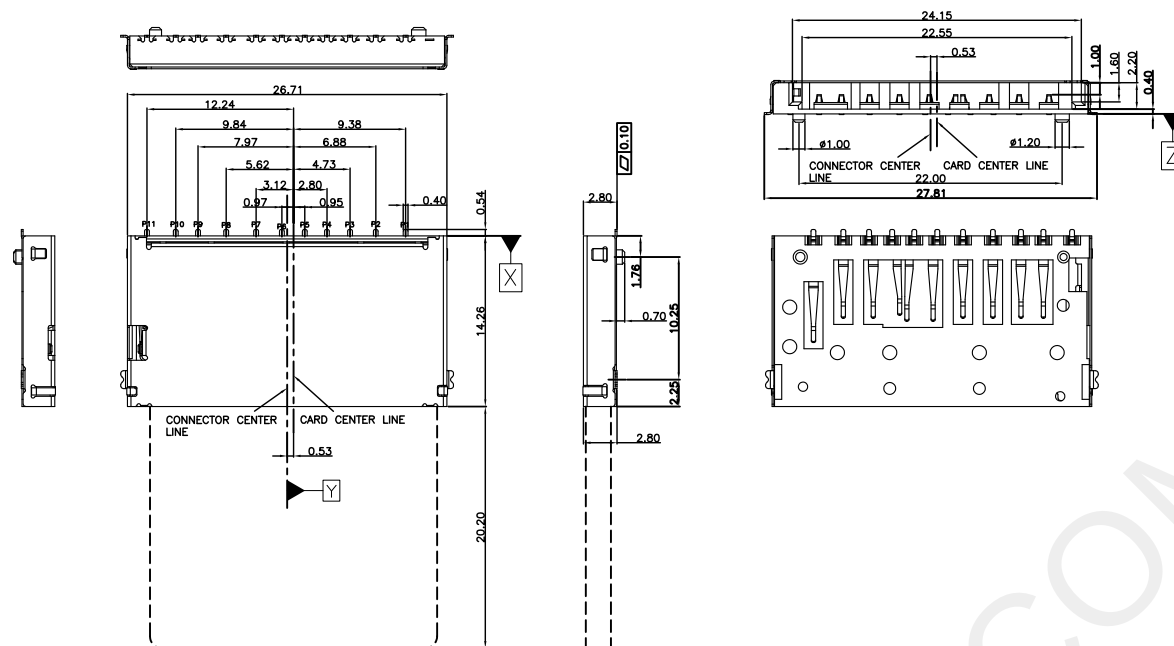




RECOMMEND P.C.B LAYOUT
TOLERANCE ± 0.05

PAD

No trace, no test point,
no via hole, no ground area

WITHOUT CARD	CARD INSERTED-LOCK	CARD INSERTED-UNLOCK
W/P GND	W/P GND	W/P GND
C/D VSS1	C/D VSS1	C/D VSS1
P3	P3	P3

Pin Define	SD Card Pin No.	Pin Define
P1	P9	DAT2
P2	P1	DAT3
P3	P2	CMD
P4		CD
P5	P3	VSS1
P6	P4	VDD
P7	P5	CLK
P8	P6	VSS2
P9	P7	DAT0
P10	P8	DAT1
P11		W/P
P12~P13		GND

NOTES :

1.Material:

- 1.1 Insulator:High Temperature Thermoplastic,
(LCP,S475),UL Black 94V-0.
- 1.2 Contact: Phosphor Bronze(C5191-EH,T=0.20 $\pm$ 0.03mm)
- 1.3 Shell: SUS304-3/4H,T=0.2 $\pm$ 0.03mm

2 Plating:

- 2.1 Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective Contact Area
Plated 80u"min Matte Sn over Ni on solder area
- 2.2 Shell: Plated 50u"min Ni Overall

3.Property:

- 3.1 Current Rating :0.5A AC/DC
- 3.2 Voltage Rating :250VRMS
- 3.3 Dielectric Withstanding Voltage: AC 500V r.m.s.
- 3.4 Insulation Resistance:1000M Ω minimum.
- 3.5 Contact Resistance:100m Ω maximum
- 3.6 Operating Temperature:-25°C~90°C
4. Part Must Comply Taisol HF WD-3-I-091 Specification.
5. Recommending A Metal More Than 0.15mm Thick. Please Confirm Solderability, IF Use A Metal Mask Less Than 0.15mm Thick.



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X' $\pm 2'$ X.X' $\pm 0.5'$	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SD NO PUSH 短体SMT 2.8H
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HVC71-SD11-280
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HVC-2503171856
			SHEET NO. 1 OF 1